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REVISION HISTORY

7/10—Revision 0: Initial Version

SPECIFICATIONS

ELECTRICAL CHARACTERISTICS

V_S = 5.0 V, V_{CM} = 0 V, T_A = 25°C, unless otherwise noted.

Table 1.

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
INPUT CHARACTERISTICS						
Offset Voltage	V_{OS}			45	325	µV
		−55°C ≤ T_A ≤ +125°C			1	mV
Input Bias Current	I_B			360	600	nA
		−55°C ≤ T_A ≤ +125°C			650	nA
Input Offset Current	I_{OS}			±2.5	±25	nA
		−55°C ≤ T_A ≤ +125°C			±40	nA
Input Voltage Range	V_{CM}		0		4	V
Common-Mode Rejection	CMRR	0 V ≤ V_{CM} ≤ 4.0 V, −55°C ≤ T_A ≤ +125°C	70	110		dB
Large Signal Voltage Gain	A_{VO}	R_L = 2 kΩ, 0.5 ≤ V_{OUT} ≤ 4.5 V		30		V/mV
		R_L = 10 kΩ, 0.5 ≤ V_{OUT} ≤ 4.5 V	65	88		V/mV
		R_L = 10 kΩ, −55°C ≤ T_A ≤ +125°C	40			V/mV
Offset Voltage Drift[1]	$\Delta V_{OS}/\Delta T$			1		µV/°C
Bias Current Drift	$\Delta I_B/\Delta T$			250		pA/°C
OUTPUT CHARACTERISTICS						
Output Voltage Swing High	V_{OH}	I_L = 250 µA, −55°C ≤ T_A ≤ +125°C	4.95	4.99		V
		I_L = 5 mA	4.85	4.94		V
Output Voltage Swing Low	V_{OL}	I_L = 250 µA, −55°C ≤T_A ≤ +125°C		14	50	mV
		I_L = 5 mA		65	150	mV
Short-Circuit Current	I_{SC}	Short to ground		±80		mA
Maximum Output Current	I_{OUT}			±30		mA
POWER SUPPLY						
Power Supply Rejection Ratio	PSRR	V_S = 2.7 V to 7 V		120		dB
		−55°C ≤ T_A ≤ +125°C	90			dB
Supply Current/Amplifier	I_{SY}	V_{OUT} = 2.5 V		500	700	µA
		−55°C ≤ T_A ≤ +125°C			850	µA
DYNAMIC PERFORMANCE						
Slew Rate	SR	1 V < V_{OUT} < 4 V, R_L = 10 kΩ		10		V/µs
Settling Time	t_S	To 0.1%, A_V = −1, V_O = 2 V step		540		ns
Gain Bandwidth Product	GBP			15		MHz
Phase Margin	φ_m			61		Degrees
NOISE PERFORMANCE						
Voltage Noise	e_n p-p	0.1 Hz to 10 Hz		0.5		µV p-p
Voltage Noise Density	e_n	f = 1 kHz		9.5		nV/√Hz
Current Noise Density	i_n	f = 1 kHz		0.4		pA/√Hz

[1] Offset voltage drift is the average of the −55°C to +25°C delta and the +25°C to +125°C delta.

V_S = 3.0 V, V_{CM} = 0 V, T_A = 25°C, unless otherwise noted.

Table 2.

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
INPUT CHARACTERISTICS						
Offset Voltage	V_{OS}			50	325	µV
		−55°C ≤ T_A ≤ +125°C			1	mV
Input Bias Current	I_B			360	600	nA
Input Offset Current	I_{OS}			±2.5	±25	nA
Input Voltage Range	V_{CM}		0		2	V
Common-Mode Rejection	CMRR	0 V ≤ V_{CM} ≤ 2.0 V, −55°C ≤ T_A ≤ +125°C	70	110		dB
Large Signal Voltage Gain	A_{VO}	R_L = 2 kΩ, 0.5 V ≤ V_{OUT} ≤ 2.5 V		20		V/mV
		R_L = 10 kΩ, 0.5 V ≤ V_{OUT} ≤ 2.5 V	20	30		V/mV
OUTPUT CHARACTERISTICS						
Output Voltage Swing High	V_{OH}	I_L = 250 µA	2.95	2.99		V
		I_L= 5 mA	2.85	2.93		V
Output Voltage Swing Low	V_{OL}	I_L = 250 µA		14	50	mV
		I_L= 5 mA		66	150	mV
POWER SUPPLY						
Power Supply Rejection Ratio	PSRR	V_S = 2.7 V to 7 V		110		dB
		−55°C ≤ T_A ≤ +125°C	60			dB
Supply Current/Amplifier	I_{SY}	V_{OUT} = 1.5 V		500	650	µA
		−55°C ≤ T_A ≤ +125°C			850	µA
DYNAMIC PERFORMANCE						
Slew Rate	SR	R_L = 10 kΩ		10		V/µs
Settling Time	t_S	To 0.1%, A_V = −1, V_O = 2 V step		575		ns
Gain Bandwidth Product	GBP			15		MHz
Phase Margin	φ_m			59		Degrees
NOISE PERFORMANCE						
Voltage Noise	e_n p-p	0.1 Hz to 10 Hz		0.5		µV p-p
Voltage Noise Density	e_n	f = 1 kHz		9.5		nV/√Hz
Current Noise Density	i_n	f = 1 kHz		0.4		pA/√Hz

V_S = ±5.0 V, V_{CM} = 0 V, T_A = 25°C, unless otherwise noted.

Table 3.

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
INPUT CHARACTERISTICS						
Offset Voltage	V_{OS}			25	325	µV
		−55°C ≤ T_A ≤ +125°C			1	mV
Input Bias Current	I_B			260	500	nA
		−55°C ≤ T_A ≤ +125°C			650	nA
Input Offset Current	I_{OS}			±2.5	±25	nA
		−55°C ≤ T_A ≤ +125°C			±40	nA
Input Voltage Range	V_{CM}		−5		+4	V
Common-Mode Rejection	CMRR	−4.9 V ≤ V_{CM} ≤ +4.0 V, −55°C ≤ T_A ≤ +125°C	70	110		dB
Large Signal Voltage Gain	A_{VO}	R_L = 2 kΩ, −4.5 V ≤ V_{OUT} ≤ +4.5 V		35		V/mV
		R_L = 10 kΩ, −4.5 V ≤ V_{OUT} ≤ +4.5 V	75	120		V/mV
		−55°C ≤ T_A ≤ +125°C	25			V/mV
Long-Term Offset Voltage[1]	V_{OS}				600	µV
Offset Voltage Drift[2]	$\Delta V_{OS}/\Delta T$			1		µV/°C
Bias Current Drift	$\Delta I_B/\Delta T$			250		pA/°C
OUTPUT CHARACTERISTICS						
Output Voltage Swing High	V_{OH}	I_L = 250 µA, −55°C ≤ T_A ≤ +125°C	4.95	4.99		V
		I_L = 5 mA	4.85	4.94		V
Output Voltage Swing Low	V_{OL}	I_L = 250 µA, −55°C ≤ T_A ≤ +125°C		−4.99	−4.95	V
		I_L = 5 mA		−4.94	−4.85	V
Short-Circuit Current	I_{SC}	Short to ground		±80		mA
Maximum Output Current	I_{OUT}			±30		mA
POWER SUPPLY						
Power Supply Rejection Ratio	PSRR	V_S = ±1.35 V to ±6 V		110		dB
		−55°C ≤ T_A ≤ +125°C	60			dB
Supply Current/Amplifier	I_{SY}	V_{OUT} = 0 V		650	800	µA
		−55°C ≤ T_A ≤ +125°C			1.15	mA
		V_{OUT} = 0 V		550	775	µA
		−55°C ≤ T_A ≤ +125°C			1	mA
Supply Voltage Range	V_S		3.0 (±1.5)		12 (±6)	V
DYNAMIC PERFORMANCE						
Slew Rate	SR	−4 V < V_{OUT} < +4 V, R_L = 10 kΩ		13		V/µs
Settling Time	t_S	To 0.1%, A_V = −1, V_O = 2 V step		475		ns
Gain Bandwidth Product	GBP			15		MHz
Phase Margin	φ_m			64		Degrees
NOISE PERFORMANCE						
Voltage Noise	e_n p-p	0.1 Hz to 10 Hz		0.5		µV p-p
Voltage Noise Density	e_n	f = 1 kHz		9.5		nV/√Hz
Current Noise Density	i_n	f = 1 kHz		0.4		pA/√Hz

[1] Long-term offset voltage is guaranteed by a 1000 hour life test performed on three independent lots at 125°C, with an LTPD of 1.3.
[2] Offset voltage drift is the average of the −55°C to +25°C delta and the +25°C to +125°C delta.

ABSOLUTE MAXIMUM RATINGS

Table 4.

Parameter	Min
Supply Voltage	±6 V
Input Voltage[1]	±6 V
Differential Input Voltage[2]	±0.6 V
Internal Power Dissipation	
SOIC (S)	Observe Derating Curves
Output Short-Circuit Duration	Observe Derating Curves
Storage Temperature Range	−65°C to +150°C
Operating Temperature Range	−55°C to +125°C
Junction Temperature Range	−65°C to +150°C
Lead Temperature Range, (Soldering, 10 sec)	300°C

[1] For supply voltages greater than 6 V, the input voltage is limited to less than or equal to the supply voltage.
[2] For differential input voltages greater than 0.6 V, the input current should be limited to less than 5 mA to prevent degradation or destruction of the input devices.

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 5.

Package Type	θ_{JA}[1]	θ_{JC}	Unit
8-Lead SOIC (R)	157	56	°C/W

[1] θ_{JA} is specified for the worst-case conditions, that is, θ_{JA} is specified for a device soldered in circuit board for SOIC package.

ESD CAUTION

ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

TYPICAL PERFORMANCE CHARACTERISTICS

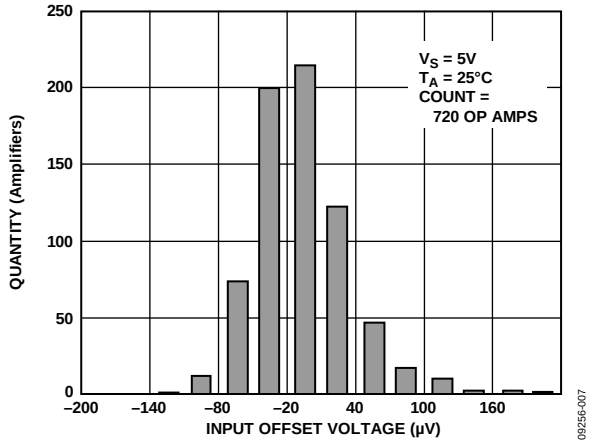


Figure 2. Input Offset Voltage Distribution

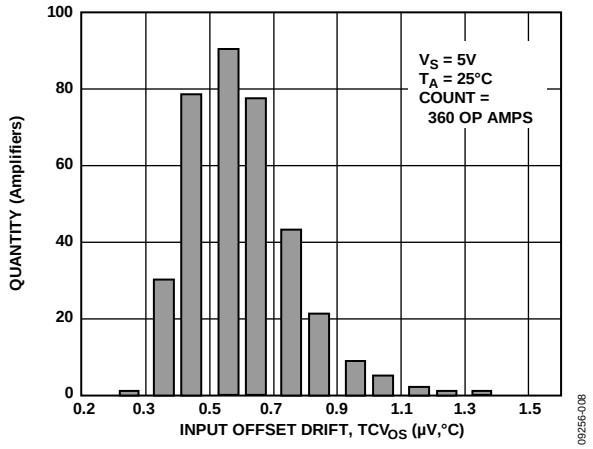


Figure 3. Input Offset Voltage Drift (TCV_{OS})

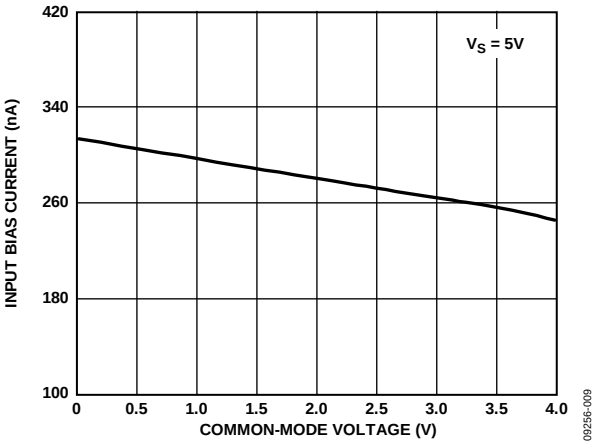


Figure 4. Input Bias Current vs. Common-Mode Voltage

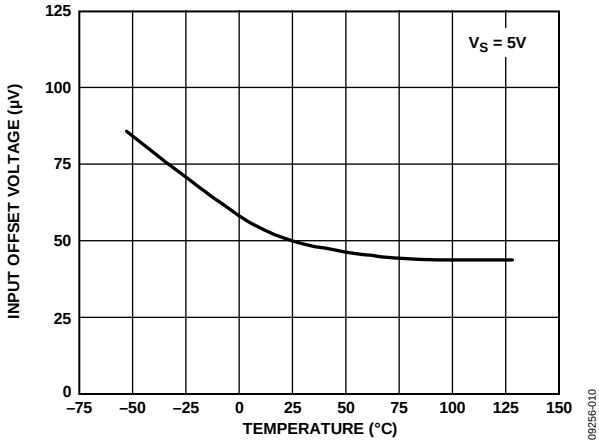


Figure 5. Input Offset Voltage vs. Temperature

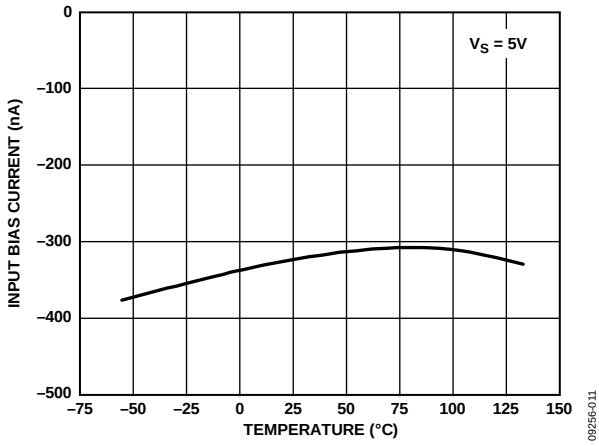


Figure 6. Input Bias Current vs. Temperature

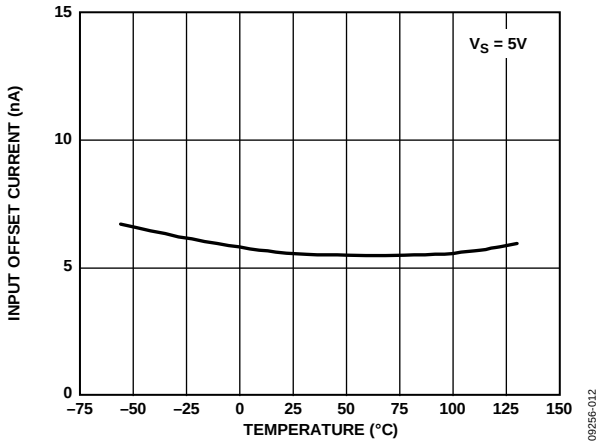


Figure 7. Input Offset Current vs. Temperature

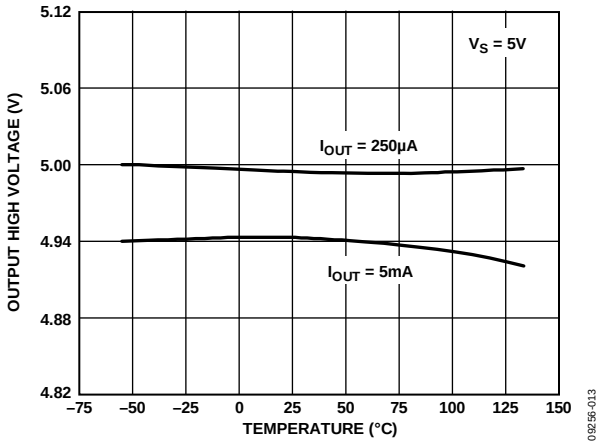


Figure 8. Output High Voltage vs. Temperature

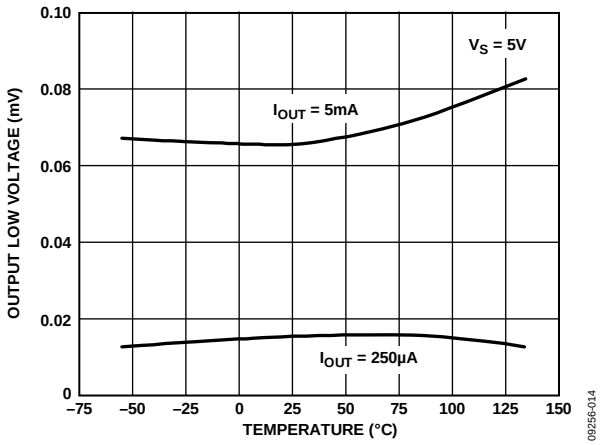


Figure 9. Output Low Voltage vs. Temperature

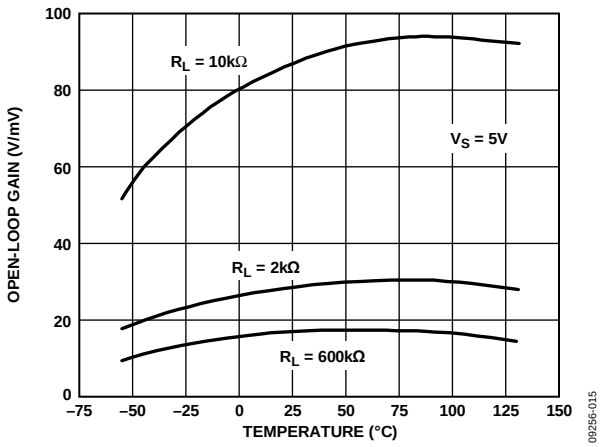


Figure 10. Open-Loop Gain vs. Temperature

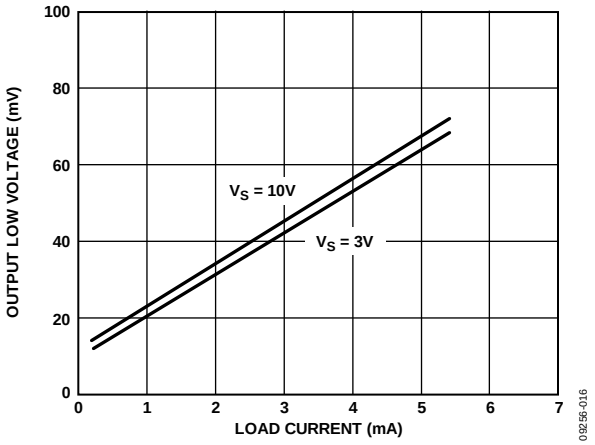


Figure 11. Output Low Voltage to Supply Rail vs. Load Current

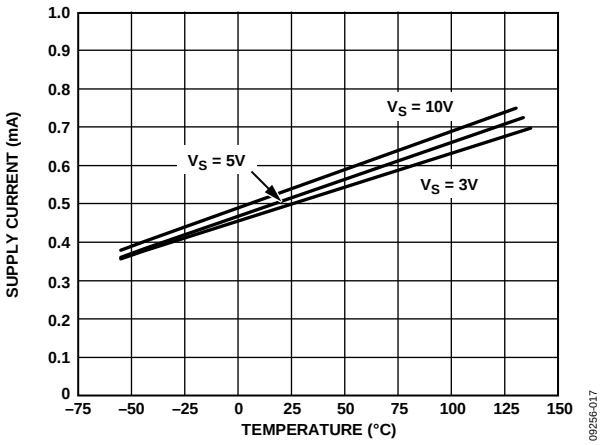


Figure 12. Supply Current/Amplifier vs. Temperature

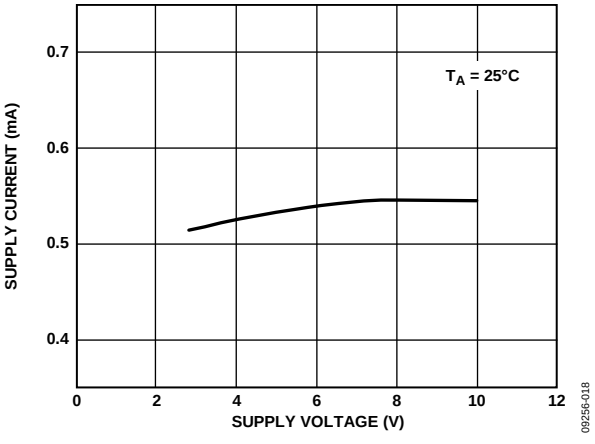


Figure 13. Supply Current/Amplifier vs. Supply Voltage

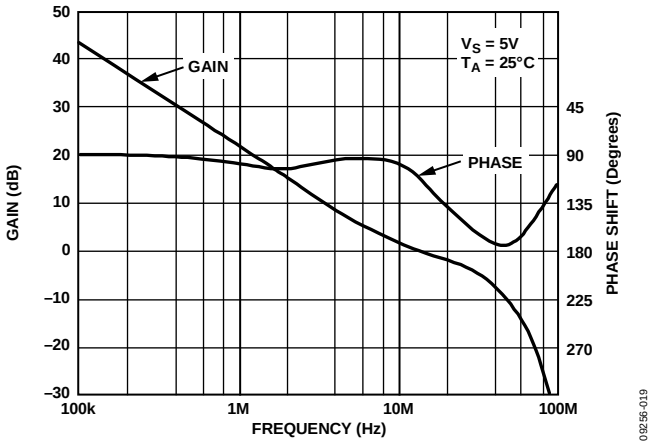


Figure 14. Open-Loop Gain and Phase vs. Frequency (No Load)

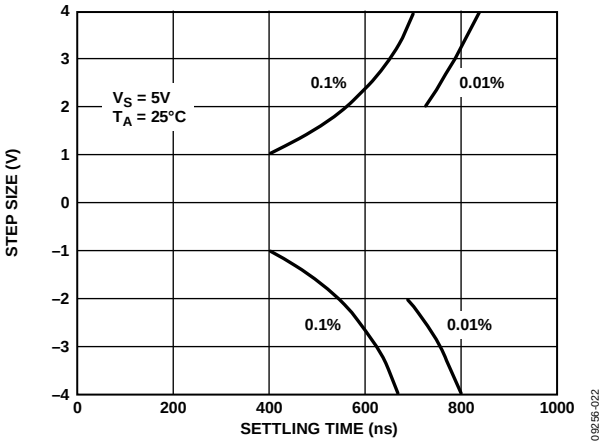


Figure 17. Step Size vs. Settling Time

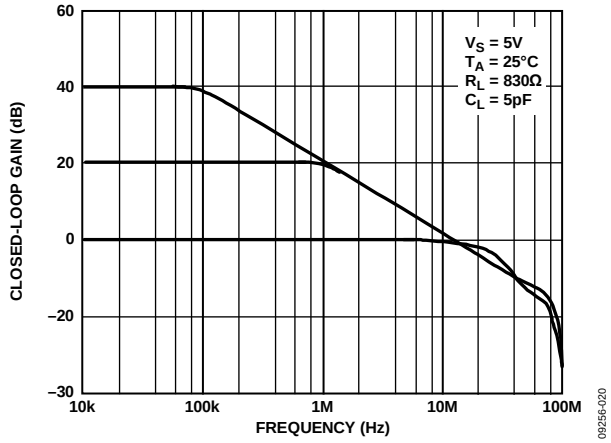


Figure 15. Closed-Loop Gain vs. Frequency

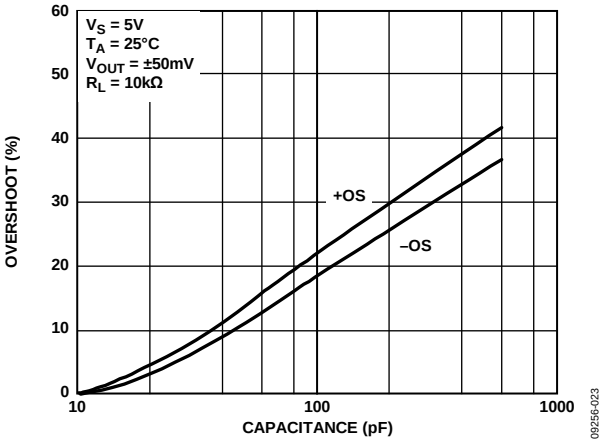


Figure 18. Small-Signal Overshoot vs. Capacitance

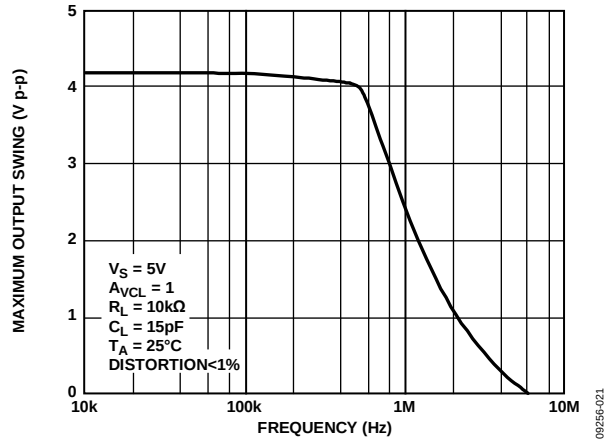


Figure 16. Maximum Output Swing vs. Frequency

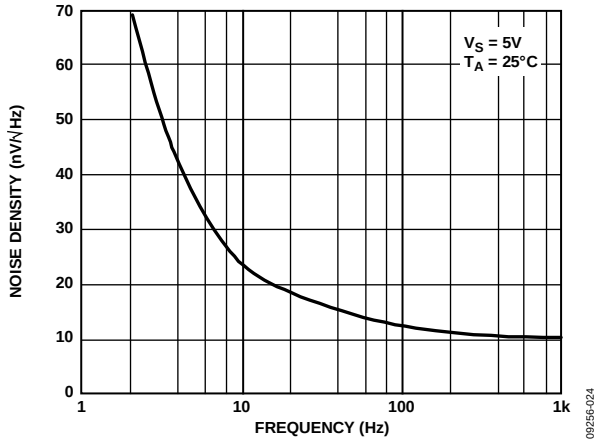


Figure 19. Voltage Noise Density vs. Frequency

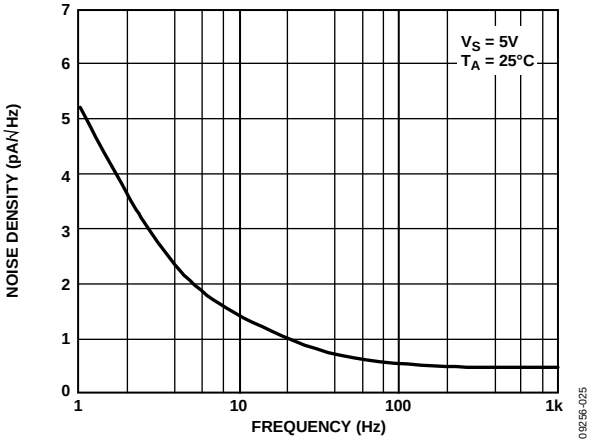


Figure 20. Current Noise Density vs. Frequency

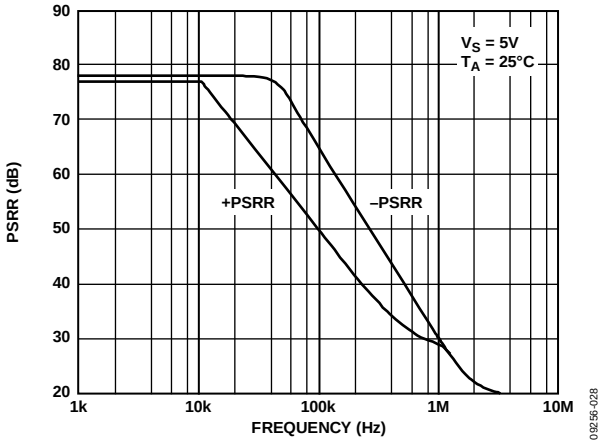


Figure 23. PSRR vs. Frequency

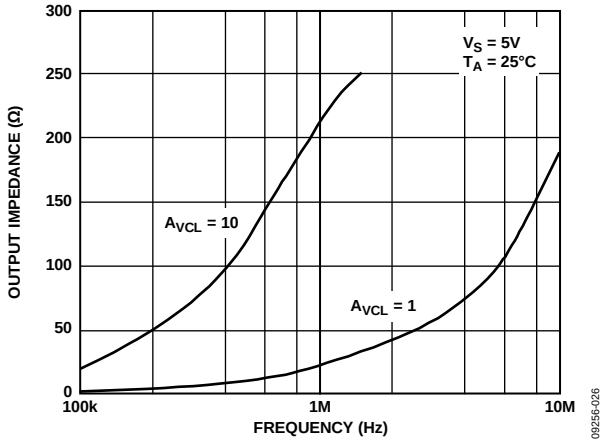


Figure 21. Output Impedance vs. Frequency

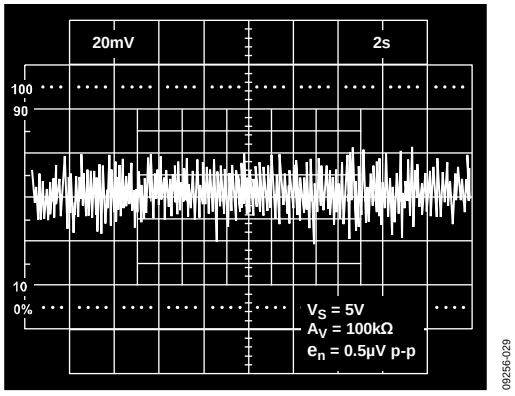


Figure 24. 0.1 Hz to 10 Hz Noise

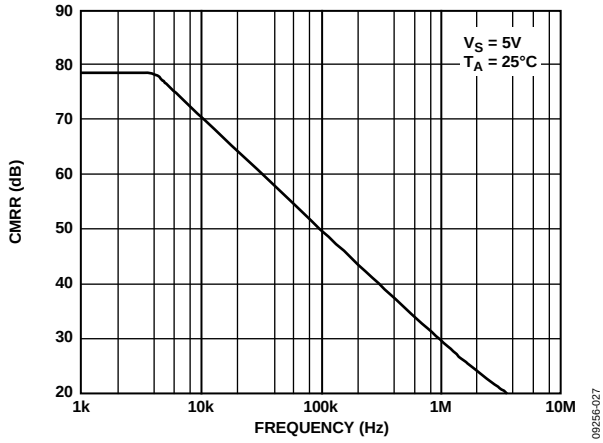


Figure 22. CMRR vs. Frequency

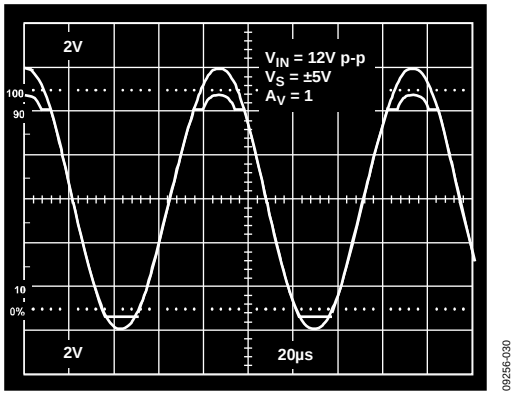
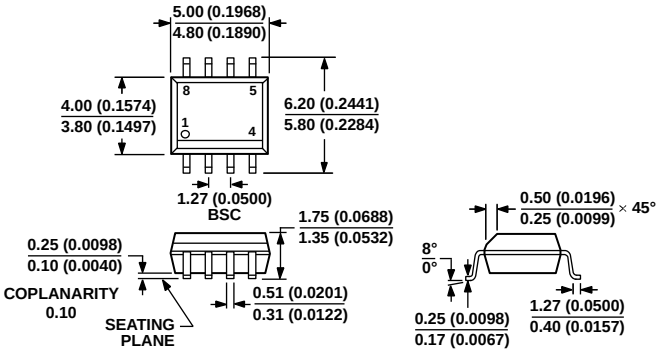


Figure 25. No Phase Reversal (V_{IN} = 12 V p-p, V_S = ±5 V, A_V = 1)

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MS-012-AA

CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS (IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

012407-A

Figure 26. 8-Lead Standard Small Outline Package [SOIC_N]
Narrow Body
(R-8)
Dimensions shown in millimeters and (inches)

ORDERING GUIDE

Model[1]	Temperature Range	Package Description	Package Option
OP262TRZ-EP	−55°C to +125°C	8-Lead Standard Small Outline Package [SOIC_N]	R-8
OP262TRZ-EP-R7	−55°C to +125°C	8-Lead Standard Small Outline Package [SOIC_N]	R-8

[1] Z = RoHS Compliant Part.

NOTES